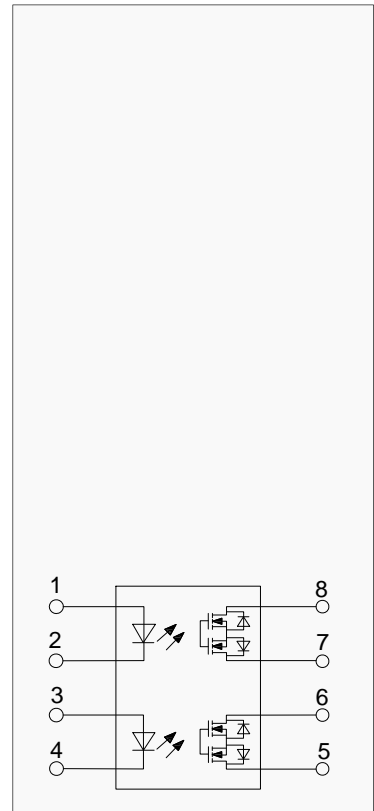




### DESCRIPTION:

The products are 8-pin optical relays. The device consists of an AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit in a plastic DIP8 package with different lead forming options. The detector consists of a high-speed photovoltaic diode array and driver circuitry. The products are widely used in isolation in high-speed inspection machines, telephones equipment and computers.



### MAIN FEATURES

- High isolation 5000 Vrms
- Wide variation of load voltage 60V to 600V
- Operating temperature range -40°C to 110°C
- REACH & RoHS compliance
- HBM: H3A; MM: M4; CDM: C3
- CQC approved
- VDE approved
- UL approved

### ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit	
Input	Forward Current	$I_F$	50	mA	
	Peak Forward Current	$I_{FP}$	1	A	
	Reverse Voltage	$V_R$	6	V	
	Input Power Dissipation	$P_D$	75	mW	
Output	Load Voltage	JOCMB39C	60	V	
		JOCMB38C	60		
		JOCMB57C	100		
		JOCMB66C	200		
		JOCMB74C	400		
		JOCMB83C	600		
	Continuous load current	$I_L$	JOCMB39C	2	A
			JOCMB38C	1	
			JOCMB57C	0.5	
			JOCMB66C	0.3	
			JOCMB74C	0.1	
			JOCMB83C	0.05	

**electronics Co., Ltd.**

800	mW
875	mW
5000	Vrms
-40~110	
125	
-40~125	
260	

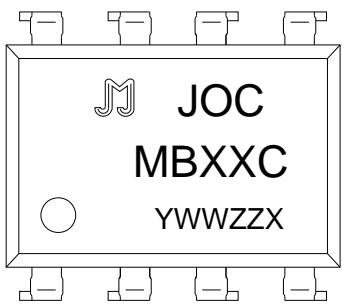
in.	Typ.	Max.	Unit
-	1.2	1.5	V
-	-	1	μA
-	0.9	3	mA
.4	0.8	-	mA
-	-	0.1	
-	-	0.3	
-	-	0.2	
-	-	2.5	

ORDERING INFORMATION

<p><b>J</b></p> <p>JieJie Microelectronics Co., Ltd.</p>	<p><b>OC</b></p> <p>Opto Coupler</p>	<p><b>M</b></p> <p>MOS</p>	<p><b>B</b></p> <p>B:2NO</p> <p>3:V<sub>O</sub>: 60V 5:V<sub>O</sub>: 100V 6:V<sub>O</sub>: 200V 7:V<sub>O</sub>: 400V 8:V : 600V</p>	<p><b>3</b></p>	<p><b>8</b></p> <p>9:I<sub>O</sub>:2A 8:I<sub>O</sub>:1A 7:I<sub>O</sub>:0.5A 6:I<sub>O</sub>:0.3A 4:I<sub>O</sub>:0.1A 3:I<sub>O</sub>:0.05A</p>	<p><b>C</b></p> <p>C:I<sub>FT</sub> 3mA</p>	<p><b>-D8P/S</b></p> <p>P:DIP8 S:SMD8</p>	<p><b>/</b></p> <p>S:T3 L:T4</p>
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Packing Quantity	
Option	Quantity

MARKING

	<p><u>YWWZZX</u></p> <p>LOT NO.</p>
---	-------------------------------------

Characteristics Curves

FIG.1: LED Dropout Voltage vs. Ambient Temperature

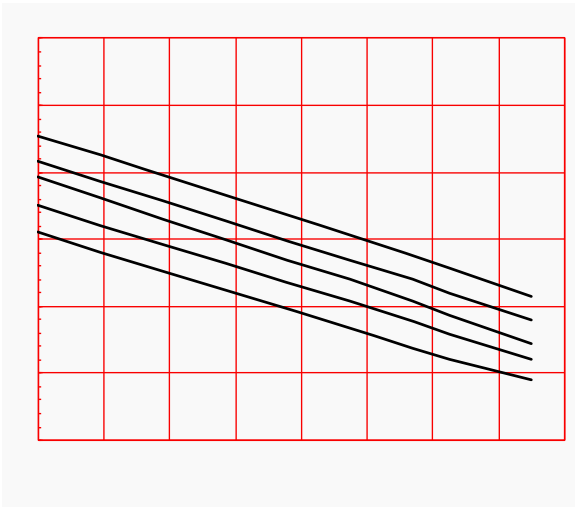


FIG.2: Output Current vs. Output Voltage

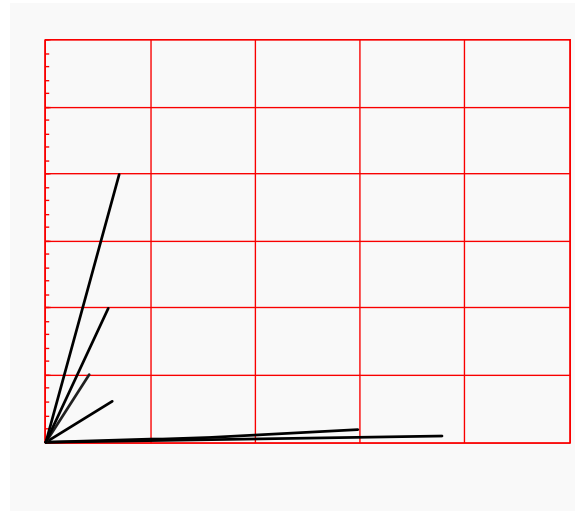


FIG.7: Turn On Time vs. Ambient Temperature

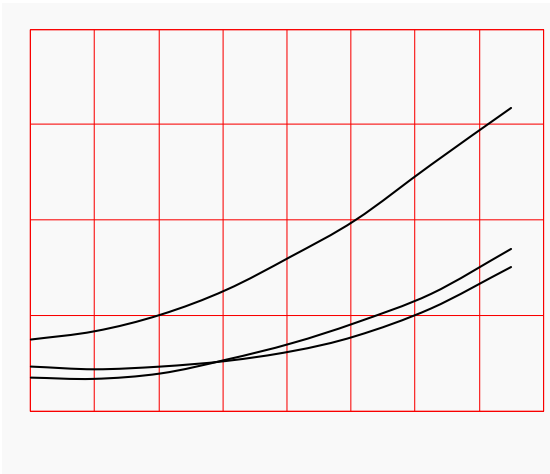


FIG.8: Turn Off Time vs. Ambient Temperature

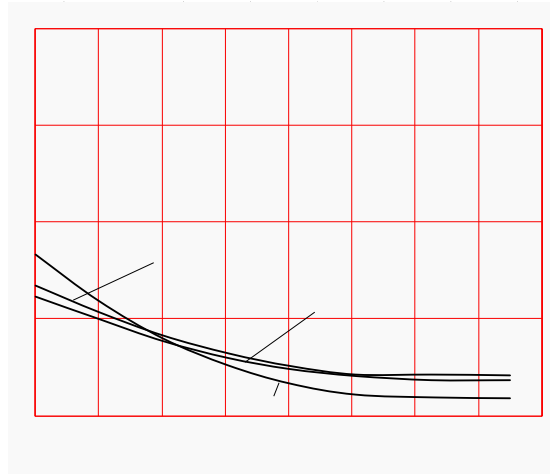


FIG.9: Turn On Time vs. LED Forward Current

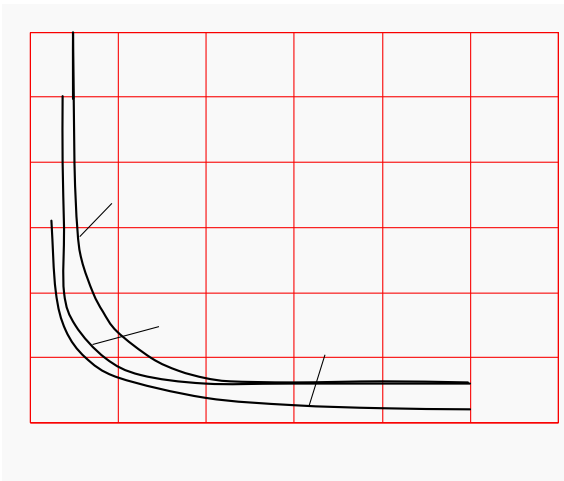


FIG.10: Turn Off Time vs. LED Forward Current

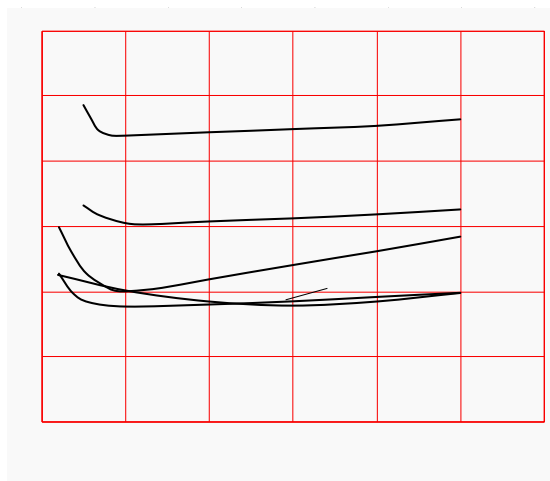


FIG.11: Off State Leakage Current vs. Load Voltage

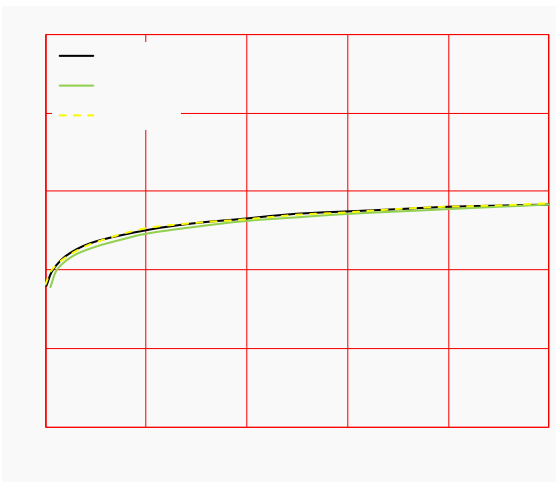
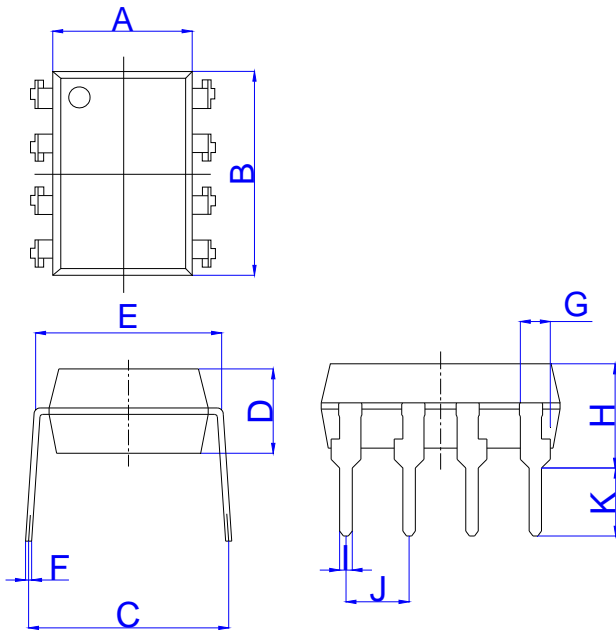


Fig.12: Turn on/Turn off time



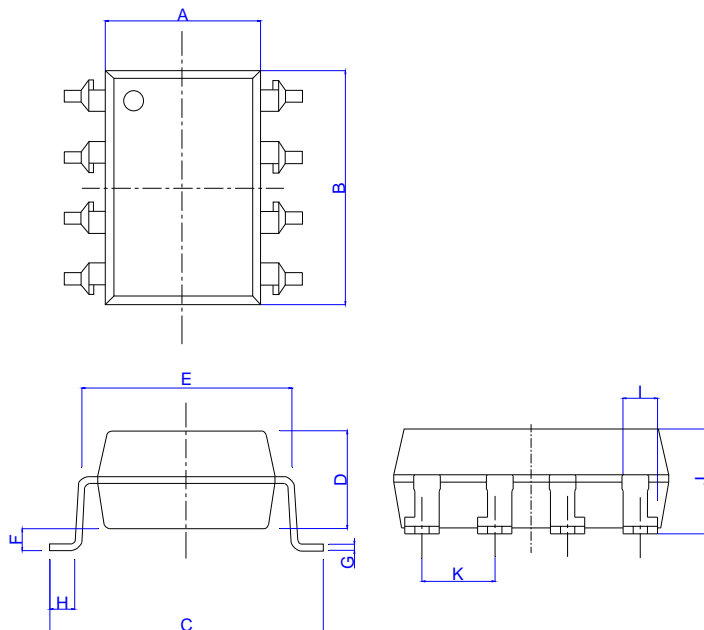
Package Dimension (Unit: mm)

Standard DIP Type:



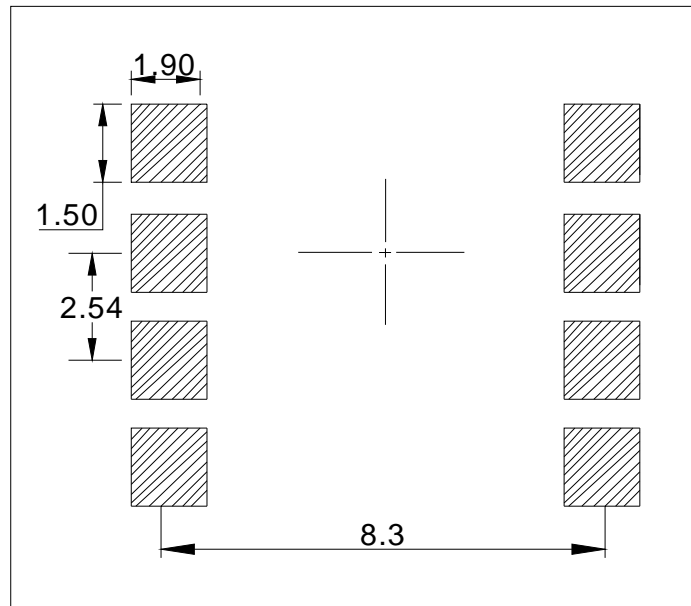
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

Option SMD Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

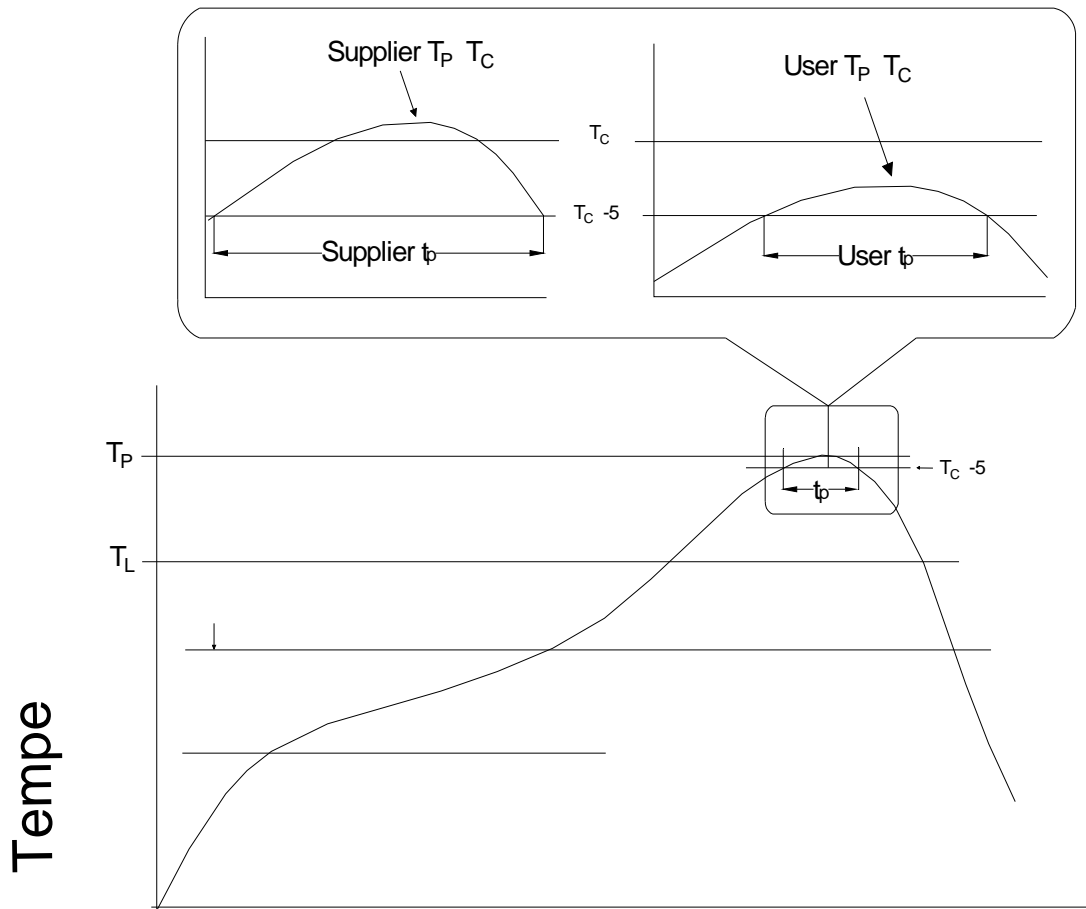
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



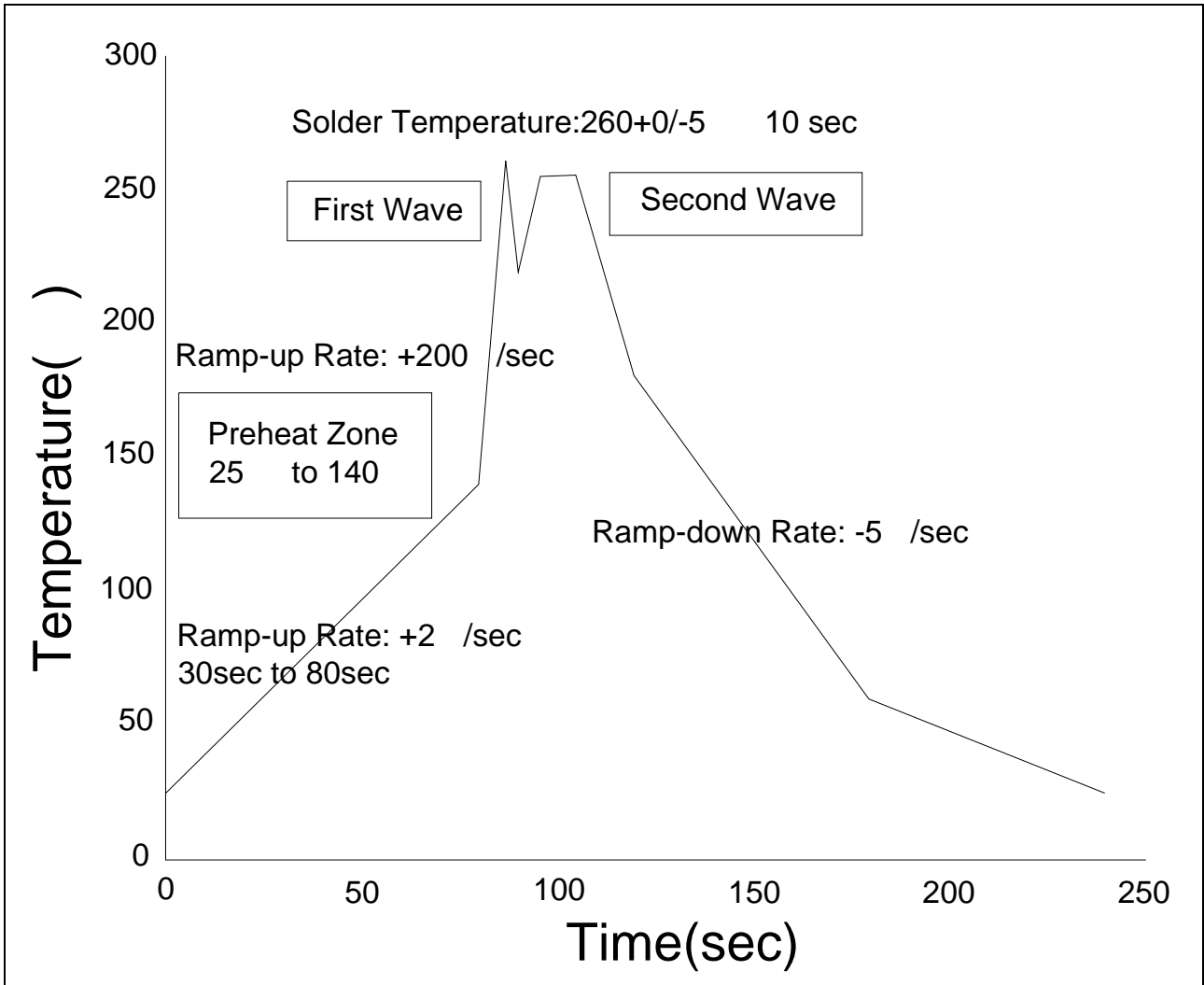
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50			0.059	
P0		4.00			0.157	
P1		12.00			0.472	
P2		2.00			0.0787	0.08
E						
F						
W		16.00			0.630	

REFLOW INFORMATION



WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON


Soldering Temperature	360± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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